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Pre Amended

EL 465852697

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

priority Application Serial No. 09/389,844
priority Filing Date September 2, 1999
Inventor Salman Akram
Assignee Micron Technology, Inc.
priority Group Art Unit 2826
priority Examiner F. Abraham
Attorney's Docket No. MI22-1572
Title: Methods Of Forming Board-On-Chip Packages (as amended)

PRELIMINARY AMENDMENT

To: BOX NON-FEE AMENDMENT
Assistant Commissioner for Patents
Washington, D.C. 20231

From: David G. Latwesen, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)
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AMENDMENTS

In the Specification

Replace the title with,

--Methods Of Forming Board-On-Chip Packages--.

At p. 1, before the "Technical Field" section, insert

--RELATED PATENT DATA

A1
This patent resulted from a divisional application of U.S. Patent Application Serial
No. 09/389,844, which was filed on September 2, 1999.--.

Amended Claims

Cancel claims 1-41.


REMARKS

Claims 1-41 are canceled, leaving claims 42-74 pending in the application. Applicant requests substantive examination of pending claims 42-74 in the Examiner's next Action.

Respectfully submitted,

Dated: January 9, 2001

By:



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